



Preliminary Exhibitor list A to Z (as of November 28, 2024)

- **3-D MID e.V. Research Association Mechatronic Integrated Devices (DE)**
- **ABeetle Corp. (TW)**
- **Advanced Electronics Materials Inc. (TW)**
- **AIMPLAS – Plastics Technology Centre (ES)**
- **AilArian Ltd (GB)**
- **Ajinomoto Fine-Techno Co., Inc. (JP)**
- **Akoneer (LT)**
- **Ames Advanced Materials Corp. (US)**
- **AMIRES s.r.o. (CZ)**
- **AMPERIAL Technology GmbH (DE)**
- **ARKEMA (FR)**
- **Asociación Cluster de Impresión Funcional y Aditiva (ES)**
- **BayflexSolutions (US)**
- **Beespenser Teknoloji Anonim Sirketi (TR)**
- **BeFC SAS (FR)**
- **Beneli AB (SE)**
- **Blackleaf (FR)**
- **BST GmbH (DE)**
- **CCI Eurolam GmbH (DE)**
- **CCL Design Stuttgart GmbH (DE)**



- **CEA-Liten** (FR)
- **Celanese Performance Solutions Germany GmbH** (DE)
- **CeNTI-Centre for Nanotechnology and Smart Materials** (PT)
- **CIDETEC Surface Engineering** (ES)
- **Coatema Coating Machinery GmbH** (DE)
- **CondAlign AS** (NO)
- **Conductive Technologies Inc.** (US)
- **Copprint** (IL)
- **COVEME s.p.a.** (IT)
- **Covestro Deutschland AG** (DE)
- **CST Colour Scanner Technology GmbH** (DE)
- **db-matik AG** (DE)
- **DELO Industrie-Klebstoffe GmbH & Co. KG aG** (DE)
- **DFV Media Group** (DE)
- **DITF - Deutsche Institute für Textil- und Faserforschung Denkendorf** (DE)
- **DICO Electronic GmbH** (DE)
- **DJK Europe GmbH** (DE)
- **DoMicro BV** (NL)
- **Dongguan Yuanguan Technology** (CN)
- **Dr. Hönle AG** (DE)



- **Dracula Technologies** (FR)
- **E INK Holdings Inc.** (US)
- **ELANTAS Europe GmbH** (DE)
- **Embega, S. Corp.** (ES)
- **ESC Europa Siebdruckmaschinen-Centrum GmbH & Co. KG** (DE)
- **EURECAT - Technology Centre** (ES)
- **Evolgene Genomics** (ES)
- **EXAKT Advanced Technologies GmbH** (DE)
- **Excelitas Technologies GmbH & Co. KG** (DE)
- **FLEXOO GmbH** (DE)
- **Föhrenbach Application Tooling NV** (BE)
- **Folex Coating GmbH** (DE)
- **Forschungszentrum Jülich GmbH** (DE)
- **Franz Binder GmbH & Co. Elektrische Bauelemente KG** (DE)
- **Fraunhofer-Institut IAP** (DE)
- **Fraunhofer-Institut IFAM** (DE)
- **Fraunhofer-Institut IKTS** (DE)
- **GM Grafisk Maskinfabrik A/S** (DK)
- **Grünig-Interscreen AG** (CH)
- **Hahn-Schickard Gesellschaft für angewandte Forschung e.V.** (DE)



- **Hamamatsu Photonics Deutschland GmbH** (DE)
- **HELIOSONIC GmbH** (DE)
- **Henkel AG & Co. KGaA** (DE)
- **Heraeus Electronics GmbH & Co. KG** (DE)
- **Heraeus Epurio GmbH** (DE)
- **HiFi Industrial Film Ltd.** (GB)
- **Highline Technology GmbH** (DE)
- **Hochschule Niederrhein** (DE)
- **Hummink** (FR)
- **HX Production Group Limited** (HK)
- **ICEX Tecnología Industrial – Spain Pavilion** (ES)
- **IEE S.A.** (LU)
- **ImageXpert LLC** (US)
- **Impressions Rotatives Offset S.A.** (ES)
- **INM - Leibniz-Institut für Neue Materialien GmbH** (DE)
- **Ino, d.o.o., Žiri** (SI)
- **ioTech – Reophotonics Ltd.** (IL)
- **ITENE** (ES)
- **JOANNEUM RESEARCH Forschungsgesellschaft mbH** (AT)
- **KELENN Technology** (FR)



- **KERAFOL Keramische Folien GmbH & Co. KG** (DE)
- **KETMarket GmbH** (DE)
- **Kimoto LTD** (CH)
- **Kundisch GmbH** (DE)
- **Kunststoff Helmbrechts AG** (DE)
- **Linxens Group** (FR)
- **M2N Media GmbH** (DE)
- **Metafas BV** (NL)
- **MGI Digital Technology** (FR)
- **MicroCraft K.K.** (JP)
- **MSWtech** (DE)
- **Nagase ChemteX America Corp.** (US)
- **Nanoinitiative Bayern GmbH** (DE)
- **Nanomatch GmbH** (DE)
- **NanoSen GmbH** (DE)
- **Nanotechnology Lab LTFN, AUTH / COPE-Nano** (GR)
- **Normandy Coating** (FR)
- **Notion Systems GmbH** (DE)
- **nsm Norbert Schlaefli AG** (CH)
- **Nuovo Film Inc.** (CN)



- **NXT GmbH** (DE)
- **OE-A (Organic and Printed Electronics Association)** (DE)
- **OES - Organic Electronics Saxony Management GmbH** (DE)
- **Panacol-Elosol GmbH** (DE)
- **Pragmatic Semiconductor Ltd.** (GB)
- **PrintCB** (IL)
- **Printup Institute Universite Paris CITE** (FR)
- **ProductionToGo GmbH** (DE)
- **Pröll GmbH** (DE)
- **PVF Mesh Screen Technology GmbH** (DE)
- **Quantica GmbH** (DE)
- **RK Siebdrucktechnik GmbH** (DE)
- **Saati S.p.A.** (IT)
- **SAL – Silicon Austria Labs GmbH** (AT)
- **Saralon GmbH** (DE)
- **SAT Electronic GmbH** (DE)
- **Schrödinger GmbH** (DE)
- **SEFAR AG** (CH)
- **Seristampa Srl** (IT)
- **ShenZhen Hochuen Technologies Co., Ltd.** (CN)



- **SignTronic AG** (CH)
- **SpeedPox GmbH** (AT)
- **SPGPrints B.V.** (NL)
- **SPT Sales & Marketing GmbH** (DE)
- **Sun Chemical Ltd** (GB)
- **Sungkyunkwan University - Institute of Quantum Biophysics** (TW)
- **Taiwan Alpha Electronics Co. Ltd.** (TW)
- **Teca-Print AG** (CH)
- **Technic Inc.** (US)
- **Tecnia Research & Innovation** (ES)
- **tesa SE** (DE)
- **Textilforschungsinstitut Thüringen - Vogtland e. V.** (DE)
- **THIEME GmbH & Co. KG** (DE)
- **TNO at Holst Centre** (NL)
- **TracXon B.V.** (NL)
- **Valver SLU** (ES)
- **VDI/VDE Innovation + Technik GmbH** (DE)
- **VDL Enabling Technologies Group** (NL)
- **Vitzrocell Co., Ltd** (KR)
- **Voltera** (CA)



- **VPF Ink Technologies** (FR)
- **VTT Technical Research Centre of Finland** (FI)
- **Wirtschaftsförderung Sachsen GmbH** (DE)
- **Witte Technology GmbH** (DE)
- **XTPL S.A.** (PL)
- **Zhejiang Kaixin Optoelectronics Technology Co., Ltd.** (CN)